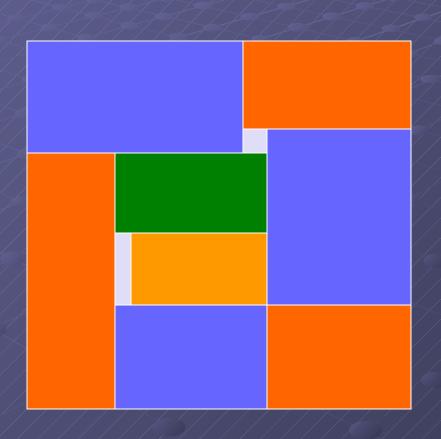
# A Fixed-die Floorplanning Algorithm Using an Analytical Approach

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#### **Outline**

- Background
- Problem formulation
- An analytical fixed-die floorplanning algorithm
- Experimental results
- Conclusions

#### Fixed-die Floorplanning Problem



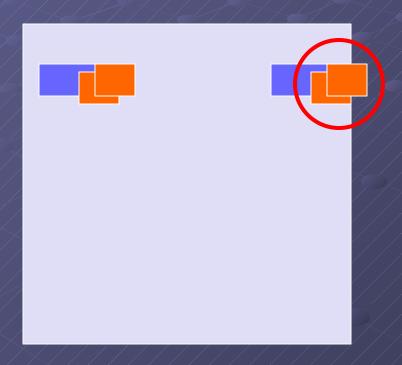
- Fixed outline
- Place and size the modules such that there is no overlap
- Minimize some delay metric, e.g., wire length

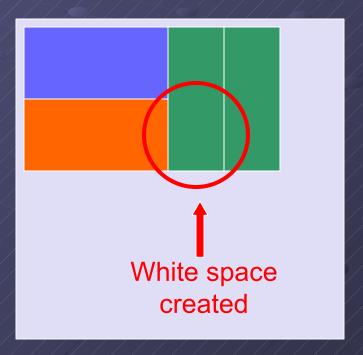
#### Previous Works

- Simulated annealing based approach
  - Adya and Markov, Trans. VLSI 2003
  - Chen and Chang, ISPD 2005
- Partition based approach
  - Cong, Romesis, and Shinnerl, ASPDAC 2005
- Analytical approach
  - Kahng and Wang, ISPD 2004 (Placement)

# Difference between Placement and Floorplanning

- Significant difference in module width and height
- Large module size





#### **Problem Formulation**

Die Size  $L_x$ ,  $L_y$ , Area and Max Aspect Ratio  $A_i$ ,  $R_i$ 

Connectivity between Modules





Analytical Floorplanner



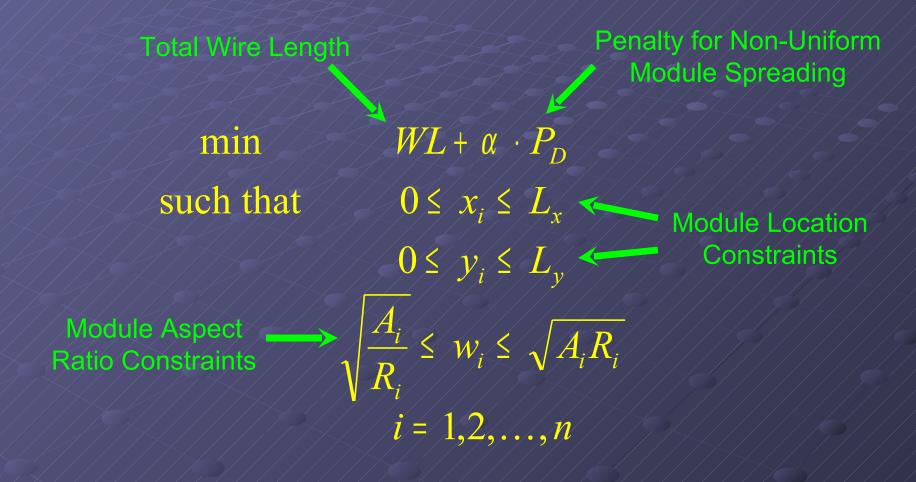
An Overlap Free Floorplan that Minimizes the Total Wire Length

### Overall Floorplanning Procedure

Rough floorplanning to spread modules uniformly with good control of total wire length (ref: Kahng and Wang, ISPD 2004)

Optimization based overlap reduction and final legalization

## Rough Floorplanning



## Transformation to the Unconstrained Optimization Problem

min 
$$WL + \alpha \cdot P_D$$
  
such that  $0 \le x_i \le L_x$   
 $0 \le y_i \le L_y$   
 $\sqrt{\frac{A_i}{R_i}} \le w_i \le \sqrt{A_i R_i}$   
 $i = 1, 2, ..., n$ 



$$\min WL + \alpha \cdot P_D + \beta \cdot B$$

#### Barrier Term

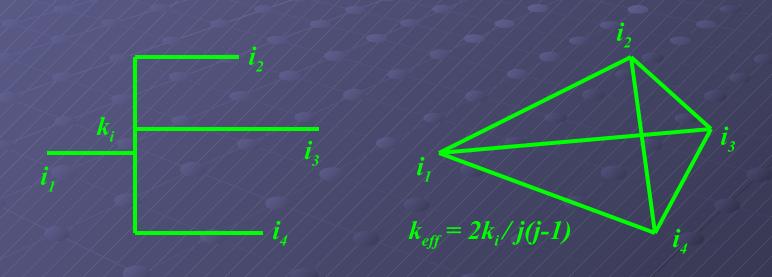
$$B = \sum_{i=1}^{n} \frac{1}{x_{i}} + \sum_{i=1}^{n} \frac{1}{L_{x} - x_{i}}$$

$$+ \sum_{i=1}^{n} \frac{1}{y_{i}} + \sum_{i=1}^{n} \frac{1}{L_{y} - y_{i}}$$

$$+ \sum_{i=1}^{n} \frac{1}{w_{i} - \sqrt{A_{i}}} + \sum_{i=1}^{n} \frac{1}{\sqrt{A_{i}R_{i}} - w_{i}}$$

## Calculation of the Total Wire Length

Clique model and quadratic wire length



$$WL = \sum_{i,j} k_{ij} [(x_i - x_j)^2 + (y_i - y_j)^2]$$

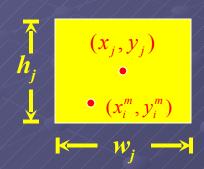
## Calculation of the Module Spreading Term

$$P_D = \sum_{i \in C_{in}} (D_i - \overline{D})^2 + \sum_{i \in C_{out}} D_i^2$$

$$\overline{D} = (\sum_{i=1}^{n} A_i)/(L_x L_y)$$

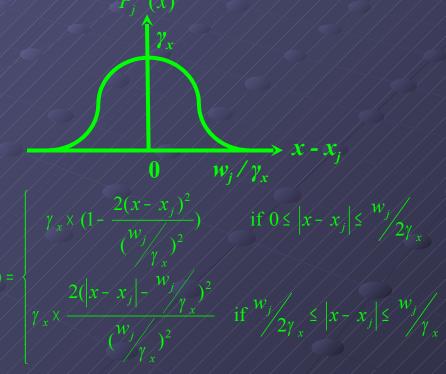
$$D_i = \sum_{j=1}^{n} \widetilde{P}_j(x_i^m, y_i^m)$$

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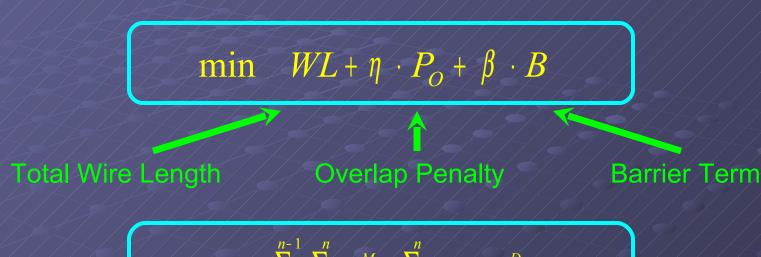


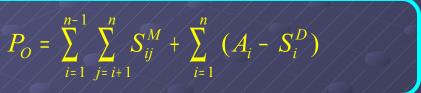
$$\widetilde{P}_{j}(x,y) = \widetilde{P}_{j}^{X}(x) \times \widetilde{P}_{j}^{Y}(y)$$

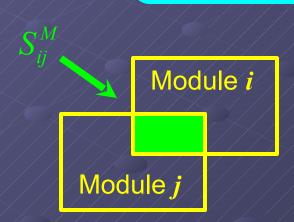
Kahng and Wang, ISPD 2004



## Overlap Reduction

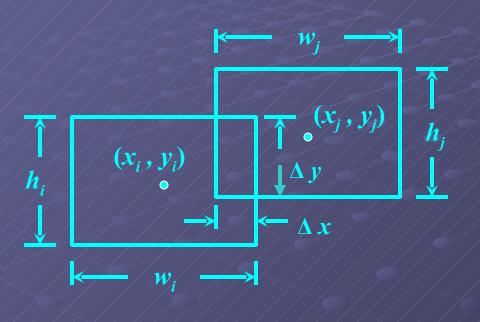


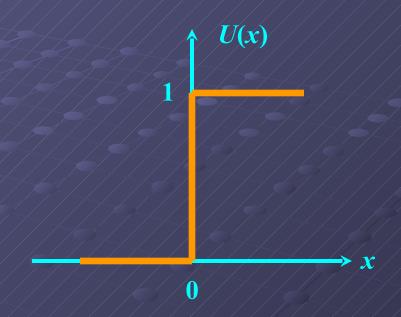






### Calculation of the Overlap Area



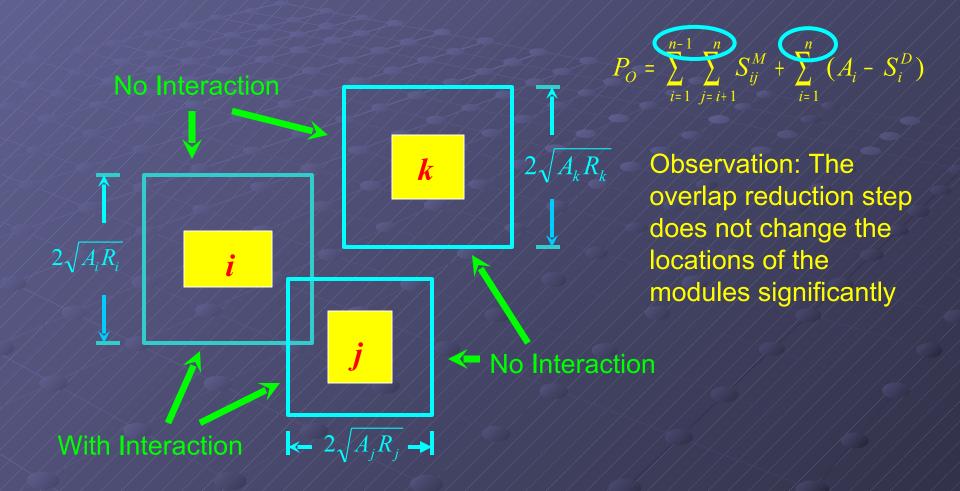


$$\Delta x = (\min\{x_i + 0.5w_i, x_j + 0.5w_j\} - \max\{x_i - 0.5w_i, x_j - 0.5w_j\})$$

$$\times U(\min\{x_i + 0.5w_i, x_j + 0.5w_j\} - \max\{x_i - 0.5w_i, x_j - 0.5w_j\})$$

$$\min\{x,y\} \approx \frac{x \cdot e^{k(y-x)} + y \cdot e^{k(x-y)}}{e^{k(x-y)} + e^{k(y-x)}}, \quad \max\{x,y\} \approx \frac{x \cdot e^{k(x-y)} + y \cdot e^{k(y-x)}}{e^{k(x-y)} + e^{k(y-x)}}, \quad U(x) \approx \frac{1}{2}(1 + \tanh(k'x))$$

### A Useful Heuristic



#### Overall Procedure

Rough Floorplanning Using Conjugate Gradient



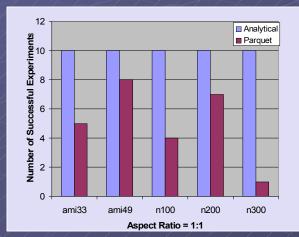
Overlap Reduction Using Conjugate Gradient

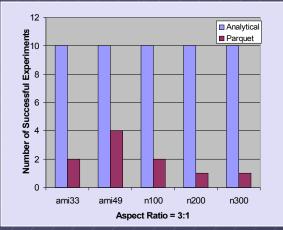


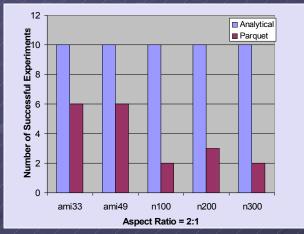
Final Legalization Using pl2sp() from Parquet

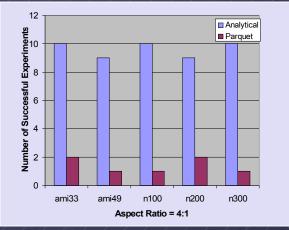
### Experimental Results

Success rate over 10 experiments (15% white space)



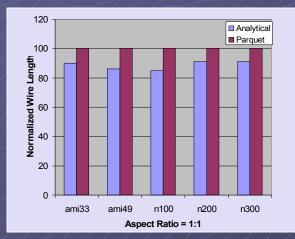


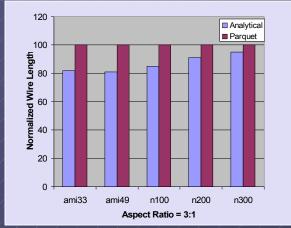


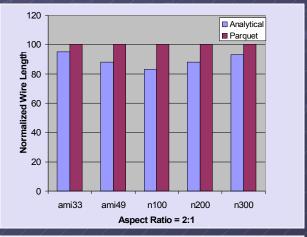


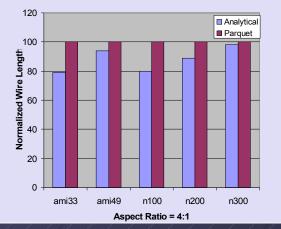
## Experimental Results

#### Wire Length



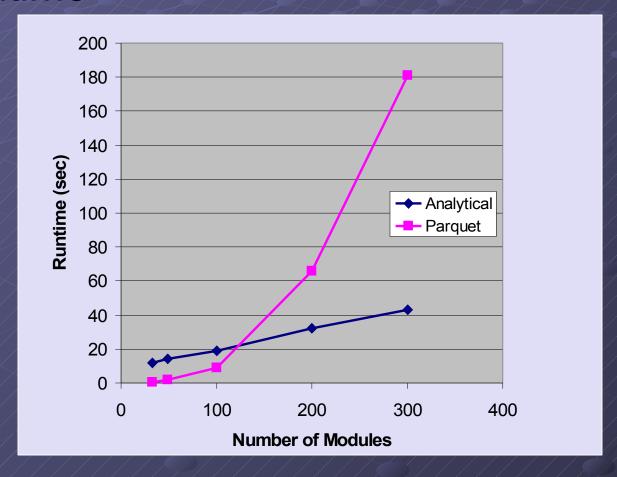






### Experimental Results

#### Runtime



#### Conclusions

- An analytical floorplanning algorithm for soft modules presented
- High success rate, good wire length, and high efficiency demonstrated